

as of March 23, 2017

Selection of ceramic microsystems-related papers

F. Schubert, M. Gollner, J. Kita, F. Linseis, R. Moos:

Optimization of a sensor for a Tian-Calvet calorimeter with LTCC-based sensor discs
Journal of Sensors and Sensors Systems, **5**, 381-388 (2016), doi: 10.5194/jsss-5-381-2016

F. Schubert, M. Gollner, J. Kita, F. Linseis, R. Moos:

First steps to develop a sensor for a Tian-Calvet calorimeter with increased sensitivity
Journal of Sensors and Sensors Systems, **5**, 205-212 (2016), doi: 10.5194/jsss-5-205-2016

A. Brandenburg, E. Wappler, J. Kita, R. Moos:

Miniaturized ceramic DSC device with strain gauge-based mass detection - First steps to realize a fully integrated DSC/TGA device
Sensors and Actuators A: Physical, **241**, 145-151 (2016), doi: 10.1016/j.sna.2016.02.011

D. Ortolino, J. Kita, K. Beart, R. Wurm, S. Kleinewig, A. Pletsch, R. Moos:

Failure of electrical vias manufactured in thick-film technology when loaded with short high current pulses
Microelectronics Reliability, **56**, 121-128 (2016), doi: 10.1016/j.microrel.2015.10.011

F. Schubert, M. Gollner, J. Kita, F. Linseis, R. Moos:

Optimierung eines neuentwickelten Sensorkopfes für ein Tian-Calvet-Kalorimeter
Sensoren und Messsysteme 2016, 10.5.-11.5.2016, Nürnberg, p. 50-52, doi: 10.5162/sensoren2016/1.2.2

F. Schubert, J. Kita, M. Gollner, F. Linseis, R. Moos:

Sensor Stack for Tian-Calvet Calorimeter made in LTCC-Technology
IMAPS/ACerS 12th International Conference and Exhibition on Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT 2016), Denver, April 19-21, 2016, p. 19-23

J. Kita, S. Wiegärtner, A. Prince, P. Weigand, R. Moos:

Evaluation of screen-printable type S (Pt-PtRh) thermocouples on different ceramic substrates
IMAPS/ACerS 12th International Conference and Exhibition on Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT 2016), Denver, April 19-21, 2016, p. 53-57

F. Schubert, M. Gollner, J. Kita, F. Linseis, R. Moos:

Neuentwicklung eines Sensorkopfes für ein Tian-Calvet-Kalorimeter
G. Gerlach, A. Schütze (Hrsg.), *12. Dresdner Sensor-Symposium*, 7.-9. Dezember 2015, Dresden, p. 222-226, doi: 10.5162/12dss2015/P7.2

G. Hagen, N. Leupold, S. Wiegärtner, J. Kita, R. Moos:

Neuartige Sensoranwendung zur Katalysator-Materialcharakterisierung
G. Gerlach, A. Schütze (Hrsg.), *12. Dresdner Sensor-Symposium*, 7.-9. Dezember 2015, Dresden, p. 230-233, doi: 10.5162/12dss2015/P7.5

J. Exner, R. Moos:

Ermittlung spezifischer Materialkennwerte von Schichten mittels Interdigital-Elektroden
G. Gerlach, A. Schütze (Hrsg.), *12. Dresdner Sensor-Symposium*, 7.-9. Dezember 2015, Dresden, p. 256-259, doi: 10.5162/12dss2015/P7.10

J. Kita, S. Wiegärtner, R. Moos, P. Weigand, A. Pliscott, M.H. LaBranche, H.D. Glicksman:

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Eurosensors XXIX, September 6 - 9, 2015, Freiburg, Germany, MP-K03
Procedia Engineering, **120**, 828-831 (2015), doi: 10.1016/j.proeng.2015.08.692

A. Brandenburg, E. Wappler, J. Kita, R. Moos:

First approaches to integrate a strain gauge-based mass detection system into a miniaturized DSC-device
Eurosensors XXIX, September 6 - 9, 2015, Freiburg, Germany, BS02-3
Procedia Engineering, **120**, 116-119 (2015), doi: 10.1016/j.proeng.2015.08.579

F. Schubert, S. Wollenhaupt, J. Kita, G. Hagen, R. Moos:

Lessons learned during the development of a manufacturing process for switching-type lambda sensors as a basis for new exhaust gas sensors
90. DKG Jahrestagung / Symposium Hochleistungskeramik 2015, Bayreuth, 15.3.-19.3.2015, p. 167

J. Kita, A. Engelbrecht, F. Schubert, A. Groß, F. Rettig, R. Moos:

Some practical points to consider with respect to thermal conductivity and electrical resistivity of ceramic substrates for high-temperature gas sensors
Sensors and Actuators B: Chemical, **213**, 541-546 (2015), doi: 10.1016/j.snb.2015.01.041

D. Ortolino, A. Engelbrecht, H. Lauterbach, M. Bräu, J. Kita, R. Moos:

Effect of Repeated Firing on the Resistance of Screen-Printed Thick Film Conductors
Journal of Ceramic Science and Technology, **5**, 317-326 (2014), doi: 10.4416/JCST2014-00029

J. Kita, A. Brandenburg, I. Sudina, R. Moos:

High-Temperature Miniaturized Furnace manufactured in HTCC-Technology
38th International Microelectronics and Packaging IMAPS Conference, Rzeszów-Czarna, Poland, 21. - 24.09.2014

- A. Brandenburg, E. Wappler, R. Moos, J. Kita:
Development and optimization of a novel miniaturized ceramic differential scanning calorimeter
Thermal Analysis and Calorimetry in Industry and Research - 40 Years of GEFTA, Berlin, Germany, September 16 - 19, 2014, p. E2
- A. Brandenburg, J. Kita, E. Wappler, R. Moos:
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- J. Kita, W. Missal, E. Wappler, F. Bechtold, R. Moos:
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Journal of Ceramic Science and Technology, **4**, 137-144 (2014), doi: 10.4416/JCST2013-00008
- A. Brandenburg, J. Kita, A. Groß, R. Moos:
Novel tube-type LTCC transducers with buried heaters and inner interdigitated electrodes as a platform for gas sensing at various high temperatures
Sensors and Actuators B: Chemical, **189**, 80-88 (2013), doi: 10.1016/j.snb.2012.12.119
- G. Hagen, J. Kita, N. Izu, U. Röder-Roith, D. Schönauer-Kamin, R. Moos:
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Sensors and Actuators B: Chemical, **187**, 174-183 (2013), doi: 10.1016/j.snb.2012.10.068
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- D. Ortolino, J. Kita, R. Moos, R. Wurm, A. Pletsch, K. Beart:
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- D. Ortolino, J. Kita, R. Wurm, E. Blum, K. Beart, R. Moos:
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35th International Microelectronics and Packaging IMAPS Conference, Gdansk, Poland 21. - 24.09.2011, p. 289-292
- M. Hrovat, D. Belavič, J. Kita, J. Holc, J. Cilenšek, S. Drnovšek:
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Journal of the European Ceramic Society, **29**, 3265–3271 (2009), doi:10.1016/j.jeurceramsoc.2009.05.019
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Sensors and Actuators B: Chemical, **139**, 394-399 (2009), doi: 10.1016/j.snb.2009.03.011
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Microelectronics Reliability, **49**, 600-606 (2009), doi: 10.1016/j.microrel.2009.02.019
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Platform for a hydrocarbon exhaust gas sensor utilizing a pumping cell and a conductometric sensor
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Laser-Shaped Thick-film Inductors Embedded in Ferrite Material
XXXIII Int'l Conference of International Microelectronics and Packaging Society IMAPS Poland, Gliwice – Pszczyna, September 21-24, 2009, p. 273-276
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Proc. of 2009 IMAPS/ACerS, 5th Intern. Conf. on Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT), Denver, Colorado, 21.4-23.4.2009

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Sensor Letters, **6**, 803-807 (2008), doi: 10.1166/sl.2008.505

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Proceedings 44th International Conference on Microelectronics, Devices and Materials, Fiesca, Slovenia, 17.-19. 9.2008, ISBN 978-961-91023-7-4, p. 3-10

M. Hrovat, D. Belavič, H. Uršič, J. Kita, J. Holc, S. Drnovšek, J. Cilenšek, M. Kosec, R. Moos:

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XXXI Int'l Conference of International Microelectronics and Packaging Society, Krasiczyn, Poland, 23.-26.9.2007, ISBN 978-83-917701-4-6, p. 401-404

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